

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
14 April 2005 (14.04.2005)

PCT

(10) International Publication Number
WO 2005/033376 A2

(51) International Patent Classification⁷: C25D 5/34, 7/12

(21) International Application Number:
PCT/JP2004/014698

(22) International Filing Date:
29 September 2004 (29.09.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
2003-345062 2 October 2003 (02.10.2003) JP
2004-035594 12 February 2004 (12.02.2004) JP

(71) Applicant (for all designated States except US): **EBARA CORPORATION** [JP/JP]; 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **KURIYAMA, Fumio** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda

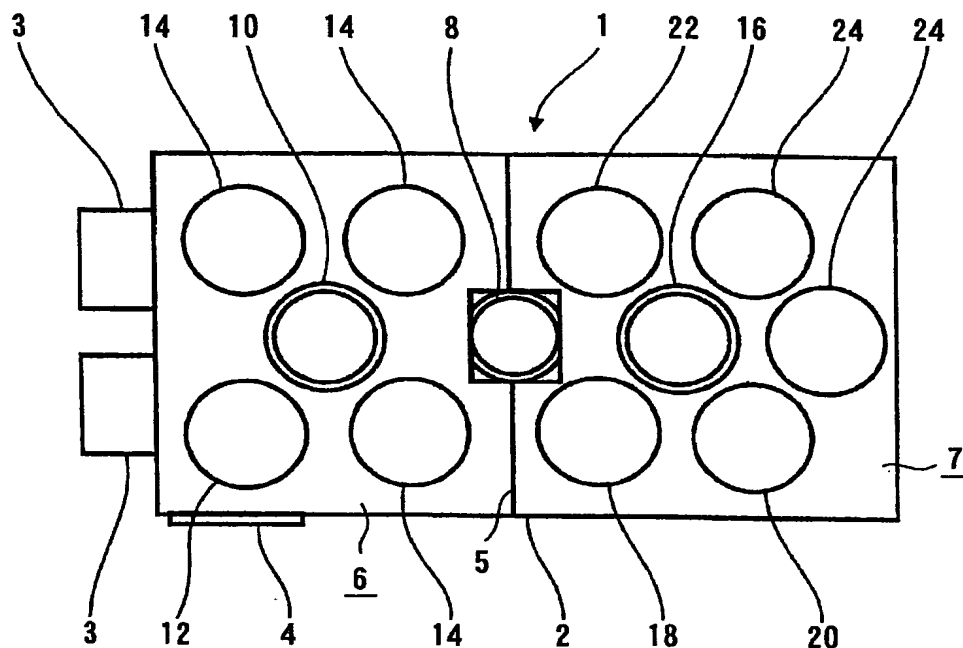
Asahi-cho, Ohta-ku, Tokyo 1448510 (JP). **KIUMI, Rei** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP). **SAITO, Nobutoshi** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP). **TAKEMURA, Takashi** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP). **KIMURA, Masaaki** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP). **TAKEDA, Sachiko** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP). **GUO, Yugang** [CN/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP).

(74) Agents: **WATANABE, Isamu** et al.; Gowa Nishi-Shinjuku 4F, 5-8, Nishi-Shinjuku 7-chome, Shinjuku-ku, Tokyo 1600023 (JP).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG,

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(54) Title: PLATING METHOD AND APPARATUS



(57) Abstract: A plating apparatus (1) has a steam treatment chamber (18) configured to perform a steam treatment using steam on a surface of a substrate (W), and a plating chamber (24) configured to plate the surface of the substrate subjected to the steam treatment. The plating apparatus also has an acid treatment chamber (20) configured to bring the surface of the substrate subjected to the steam treatment into contact with an acid liquid. The plating apparatus includes a frame (2) housing the steam treatment chamber (18), the acid treatment chamber (20), and the plating chamber (24).

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KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— without international search report and to be republished upon receipt of that report

- (84) **Designated States** (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI,

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